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103515324

OMB No. 0651-0011 (exp. 4/94)

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):  
  
Jong-han JEONG, Jae-kyeong JEONG, Jin-seong PARK, Yeon-gon MO, Hui-won YANG, Min-kyu KIM, Tae-kyung AHN, Hyun-soo SHIN, Hun-jung LEE  
  
Additional name(s) of conveying party(ies) attached? No

2. Name and address of receiving party(ies):  
  
Name: Samsung SDI Co., Ltd.  
Internal Address:  
Street Address: 575, Shin-dong, Yeongtong-gu,  
City: Suwon-si, Gyeonggi-do 442-731, REPUBLIC OF KOREA  
  
Additional name(s) & address(es) attached? No

3. Nature of conveyance:  
 Assignment                      Merger  
      Security Agreement            Change of Name  
      Other

Execution Date: July 11, 2008

4. Application number(s) or patent number(s):  
  
If this document is being filed together with a new application, the execution date of the application is: July 11, 2008  
A. Patent Application No.(s)  
  
Additional numbers attached? No

B. Patent No.(s)

5. Name and address of party to whom correspondence concerning document should be mailed:  
  
Name: Eugene M. Lee  
Internal Address: LEE & MORSE, P.C.  
Street Address: 3141 Fairview Park Drive, Suite 500  
City: Falls Church, State: VA ZIP: 22042

6. Total number of applications and patents involved: One

7. Total fee (37 C.F.R. 3.41).....\$40.00  
 Enclosed (PTO-2038)  
 Authorized to be charged to deposit account any additional fees

8. Deposit account number: 5-01645  
  
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9. Statement and signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Eugene M. Lee  
Name of Person Signing  
Attorney Docket No.: 304/123

Signature

July 15, 2008  
Date

Total number of pages including cover sheet, attachments, and document: 2 pages attached, incl. cover

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Alexandria, VA. 22313

# ASSIGNMENT

Name and Address of Assignee	For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto <b>SAMSUNG SDI CO., LTD.,</b> <b>575, Shin-dong, Yeongtong-gu, Suwon-si,</b> <b>Gyeonggi-do, Republic of Korea</b>
	(hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to his invention relating to

Title of Invention	<b>METHOD OF MANUFACTURING SEMICONDUCTOR ACTIVE LAYER, METHOD OF MANUFACTURING THIN FILM TRANSISTOR USING THE SAME AND THIN FILM TRANSISTOR HAVING SEMICONDUCTOR ACTIVE LAYER</b> as set forth in this United States Patent Application
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Check One	<input checked="" type="checkbox"/> executed concurrently herewith <input type="checkbox"/> executed on _____ <input type="checkbox"/> Serial No. _____ Filed _____
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in and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States which may issue on any such application or for said invention, including any and all reissues or extensions thereof, to be held and enjoyed by said ASSIGNEE, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to said ASSIGNEE, its successors or assigns in accordance herewith;

Each of the undersigned warrants and covenants that he has the full and unencumbered right to sell and assign the interests herein sold and assigned and that he has not executed and will not execute any document or instrument in conflict herewith;

Each of the undersigned further covenants and agrees he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said invention or patent application and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said invention, to said application including divisions and continuations thereof and to any and all Letters Patent which may be granted therefore or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention;

Each of the undersigned hereby grants the firm of LEE & MORSE, P.C. the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

## NAMES AND SIGNATURES OF INVENTORS

Name: <b>JEONG, Jong-han</b>	Signature:	Date: <b>July 11, 2008</b>
Name: <b>JEONG, Jae-kyeong</b>	Signature:	Date: <b>July 11, 2008</b>
Name: <b>PARK, Jin-seong</b>	Signature:	Date: <b>July 11, 2008</b>
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Name: <b>AHN, Tae-kyung</b>	Signature:	Date: <b>July 11, 2008</b>
Name: <b>SHIN, Hyun-soo</b>	Signature:	Date: <b>July 11, 2008</b>
Name: <b>LEE, Hun-jung</b>	Signature:	Date: <b>July 11, 2008</b>

PATENT